PWP PACKAGE

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- Compatible With PC 99 Desktop Line-Out Into 10-k Ω Load Compatible With PC 99 Portable Into 8- Ω
- Internal Gain Control, Which Eliminates **External Gain-Setting Resistors**
- 2-W/Ch Output Power Into 3- Ω Load
- **PC-Beep Input**
- **Depop Circuitry**
- **Stereo Input MUX**
- **Fully Differential Input**
- **Low Supply Current and Shutdown Current**
- **Surface-Mount Power Packaging** 24-Pin TSSOP PowerPAD™

	(TOP VIEW)		
GND GAINO GA	1 O 2 3 4 5 6 7 8 9 10 11 12	24 23 22 21 20 19 18 17 16 15 14 13	GND RLINEIN SHUTDOWN ROUT+ RHPIN VDD PVDD PCB ENABLE ROUT- SE/BTL PC-BEEP GND

description

The TPA0122 is a stereo audio power amplifier in a 24-pin TSSOP thermally enhanced package capable of delivering 2 W of continuous RMS power per channel into 3- Ω loads. This device minimizes the number of external components needed, simplifying the design, and freeing up board space for other features. When driving 1 W into $8-\Omega$ speakers, the TPA0122 has less than 0.5% THD+N across its specified frequency range.

Included within this device is integrated depop circuitry that virtually eliminates transients that cause noise in the speakers.

Amplifier gain is internally configured and controlled by two terminals (GAIN0 and GAIN1). BTL gain settings of 2, 6, 12, and 24 V/V are provided, while SE gain is always configured as 1 V/V for headphone drive. An internal input MUX allows two sets of stereo inputs to the amplifier. In notebook applications, where internal speakers are driven as BTL and the line outputs (often headphone drive) are required to be SE, the TPA0122 automatically switches into SE mode when the SE/BTL input is activated, and reduces the gain to 1 V/V.

The TPA0122 consumes only 18 mA of supply current during normal operation. A miserly shutdown mode reduces the supply current to less than 150 μA.

The PowerPAD package (PWP) delivers a level of thermal performance that was previously achievable only in TO-220-type packages. Thermal impedances of approximately 35°C/W are truly realized in multilayer PCB applications. This allows the TPA0122 to operate at full power into 8- Ω loads at an ambient temperature of 85 $^{\circ}$ C.



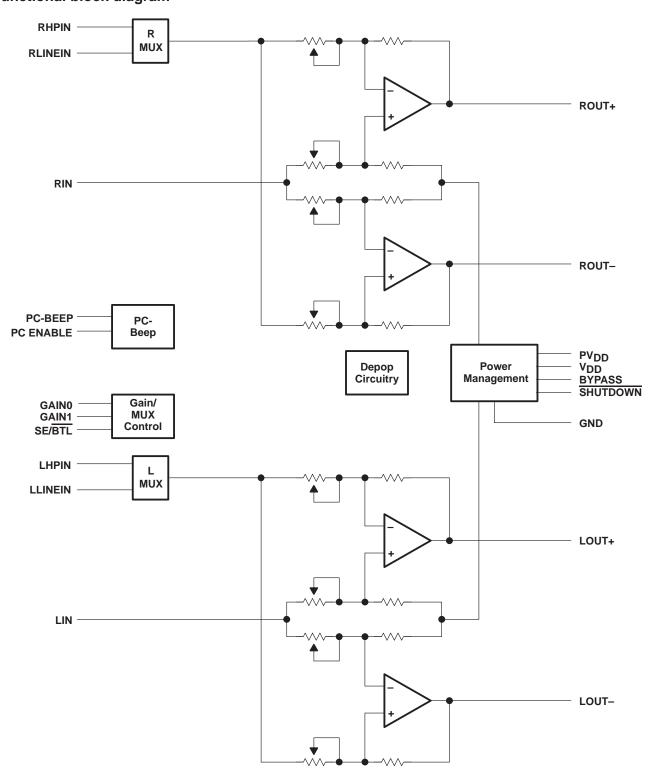
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functional block diagram





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AVAILABLE OPTIONS

	PACKAGED DEVICE
TA	TSSOP [†]
	(PWP)
-40°C to 85°C	TPA0122PWP

The PWP package is available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0122PWPR).

Terminal Functions

TERMINAL						
NAME	NO.	I/O	DESCRIPTION			
BYPASS	11		Tap to voltage divider for internal mid-supply bias generator			
GAIN0	2	I	Bit 0 of gain control			
GAIN1	3	I	Bit 1 of gain control			
GND	1, 12, 13, 24		Ground connection for circuitry. Connected to the thermal pad			
LHPIN	6	I	Left channel headphone input, selected when SE/BTL is held high			
LIN	10	ı	Common left input for fully differential input. AC ground for single-ended inputs			
LLINEIN	5	ı	Left channel line input, selected when SE/BTL is held low			
LOUT+	4	0	Left channel positive output in BTL mode and positive output in SE mode			
LOUT-	9	0	Left channel negative output in BTL mode and high-impedance in SE mode			
PC-BEEP	14	I	The input for PC Beep mode. PC-BEEP is enabled when a > 1-V (peak-to-peak) square wave is input to PC-BEEP or PCB ENABLE is high.			
PCB ENABLE	17	I	If this terminal is high, the detection circuitry for PC-BEEP is overridden and passes PC-BEEP through the amplifier, regardless of its amplitude. If PCB ENABLE is floating or low, the amplifier continues to operate normally.			
PV_{DD}	7, 18	I	Power supply for output stage			
RHPIN	20	ı	Right channel headphone input, selected when SE/BTL is held high			
RIN	8	ı	Common right input for fully differential input. AC ground for single-ended inputs			
RLINEIN	23	I	Right channel line input, selected when SE/BTL is held low			
ROUT+	21	0	Right channel positive output in BTL mode and positive output in SE mode			
ROUT-	16	0	Right channel negative output in BTL mode and high-impedance in SE mode			
SHUTDOWN	22	I	Places entire IC in shutdown mode when held low, except PC-BEEP remains active			
SE/BTL	15	ı	Input MUX control input. When this terminal is held high, the LHPIN or RHPIN and SE output is selected. When this terminal is held low, the LLINEIN or RLINEIN and BTL output are selected.			
V_{DD}	19	I	Analog V _{DD} input supply. This terminal needs to be isolated from PV _{DD} to achieve highest performance.			



TPA0122 STEREO 2-W AUDIO POWER AMPLIFIER WITH FOUR SELECTABLE GAIN SETTINGS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD}	6 V
Input voltage, V _I	0.3 V to V _{DD} +0.3 V
Continuous total power dissipation	internally limited (see Dissipation Rating Table)
Operating free-air temperature range, T _A	–40°C to 85°C
Operating junction temperature range, T _J	–40°C to 150°C
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 secon	nds 260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \leq 25^{\circ}\mbox{C}$	DERATING FACTOR	T _A = 70°C	T _A = 85°C
PWP	2.7 W [‡]	21.8 mW/°C	1.7 W	1.4 W

[‡] Please see the Texas Instruments document, *PowerPAD Thermally Enhanced Package Application Report* (literature number SLMA002), for more information on the PowerPAD package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of the before mentioned document.

recommended operating conditions

		М	N	MAX	UNIT	
Supply voltage, V _{DD}		4	.5	5.5	V	
High-level input voltage, V _{IH}	SE/BTL		4			
	SHUTDOWN		2		l v	
Low-level input voltage, V _{IL}	SE/BTL			3	1/	
	SHUTDOWN			0.8	V	
Operating free-air temperature, TA		-4	10	85	°C	



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electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
IVODI	Differential output voltage				25	mV
PSRR	Power supply rejection ratio	$V_{DD} = 4.9 \text{ V to } 5.1 \text{ V}$		77		dB
Інні	High-level input current	$V_{DD} = 5.5 \text{ V},$ $V_{I} = V_{DD}$			900	nA
IIL	Low-level input current	V _{DD} = 5.5 V, V _I = 0 V			900	nA
IDD	Supply current	BTL mode		18		mA
		SE mode		9		IIIA
I _{DD(sd)}	Supply current, shutdown mode			150	300	μΑ

operating characteristics, V_{DD} = 5 V, T_A = 25°C, R_L = 8 Ω , Gain = –2 V/V, BTL mode

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
PO	Output power	THD = 1%, $R_L = 4 \Omega$	f = 1 kHz,	,	1.9		W
THD + N	Total harmonic distortion plus noise	P _O = 1 W,	f = 20 Hz to 15 kHz		0.5%		
ВОМ	Maximum output power bandwidth	THD = 5%			>15		kHz
ksvr	Supply ripple rejection ratio	f = 1 kHz, C _B = 0.47 μF	BTL mode		68		dB
SNR	Signal-to-noise ratio		•		105		dB
V _n	Noise output voltage	$C_B = 0.47 \mu F$	BTL mode		16		\/
		f = 20 Hz to 20 kHz	SE mode		30	·	^{μV} RMS
Z _i	Input impedance				>10	·	kΩ

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APPLICATION INFORMATION

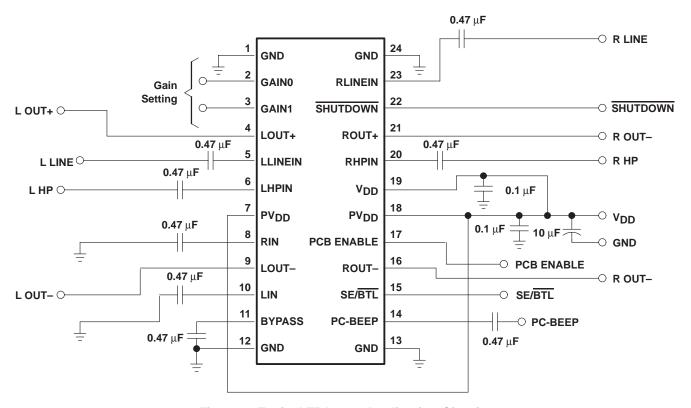


Figure 1. Typical TPA0122 Application Circuit



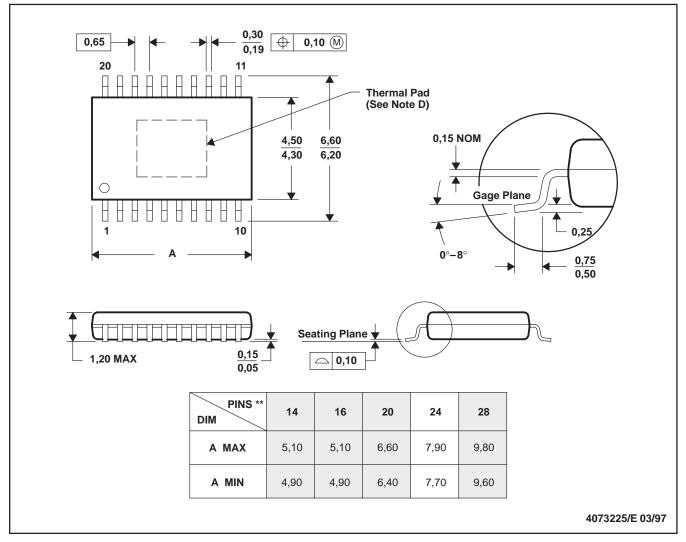
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MECHANICAL DATA

PWP (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20-PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusions.
 - D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
 - E. Falls within JEDEC MO-153

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